



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SSOT-23					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	320	162 500	200 °C + N2	0	0.00
HAST	902	90 200	130 °C, 85 % RH	0	0.00
Power Cycle	410	6 150 000	DELTA T _J = 100 °C	0	0.00
Pressure Pot	902	86 592	121°, 15 PSIG	0	0.00
Solder DUNK	467	1401	260 °C, 10 s	0	0.00
Solderability	105	840	883 M2003	0	0.00
Temp. Cycle	902	902 000	-55 °C to 150 °C	0	0.00